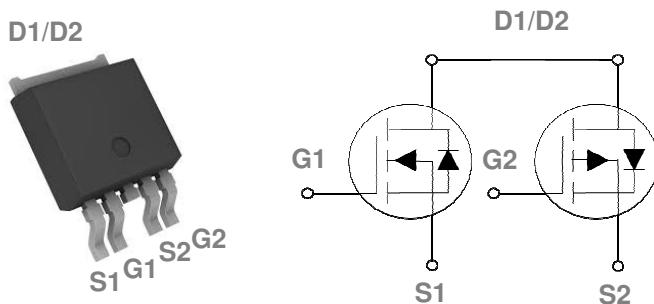


General Description

These N+P dual Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

TO252-4L Pin Configuration



BVDSS	RDS(on)	ID
30V	12mΩ	16A
-30V	30mΩ	-12A

Features

- Fast switching
- Green Device Available
- Suit for 4.5V Gate Drive Applications

Applications

- DC Fan
- Motor Drive Applications
- Networking
- Half / Full Bridge Topology

Absolute Maximum Ratings $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rating		Units
V_{DS}	Drain-Source Voltage	30	-30	V
V_{GS}	Gate-Source Voltage	± 20	± 20	V
I_D	Drain Current – Continuous ($T_c=25^\circ\text{C}$)	16	-12	A
	Drain Current – Continuous ($T_c=100^\circ\text{C}$)	10.1	-7.6	A
I_{DM}	Drain Current – Pulsed ¹	64	-48	A
P_D	Power Dissipation ($T_c=25^\circ\text{C}$)	32.5		W
	Power Dissipation – Derate above 25°C	0.26		W/°C
T_{STG}	Storage Temperature Range	-55 to 150		°C
T_J	Operating Junction Temperature Range	-55 to 150		°C

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	62.5	°C/W
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	3.84	°C/W

N-CH Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise) noted
Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$, $I_D=250\mu\text{A}$	30	---	---	V
I_{DSS}	Drain-Source Leakage Current	$V_{\text{DS}}=30\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=25^\circ\text{C}$	---	---	1	μA
		$V_{\text{DS}}=24\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=125^\circ\text{C}$	---	---	10	μA
I_{GSS}	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$, $V_{\text{DS}}=0\text{V}$	---	---	± 100	nA

On Characteristics

$\text{R}_{\text{DS(ON)}}$	Static Drain-Source On-Resistance	$V_{\text{GS}}=10\text{V}$, $I_D=10\text{A}$	---	9.4	12	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$, $I_D=5\text{A}$	---	13	18	$\text{m}\Omega$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$, $I_D = 250\mu\text{A}$	1.2	1.6	2.5	V
$\Delta V_{\text{GS(th)}}$	$V_{\text{GS(th)}}$ Temperature Coefficient		---	-4	---	$\text{mV}/^\circ\text{C}$
gfs	Forward Transconductance	$V_{\text{DS}}=10\text{V}$, $I_D=3\text{A}$	---	6	---	S

Dynamic and switching Characteristics

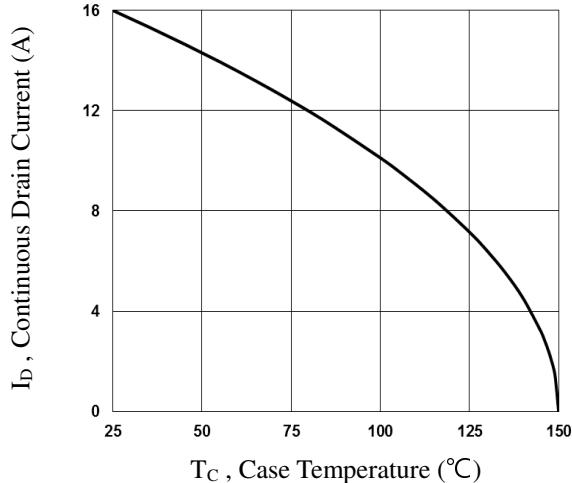
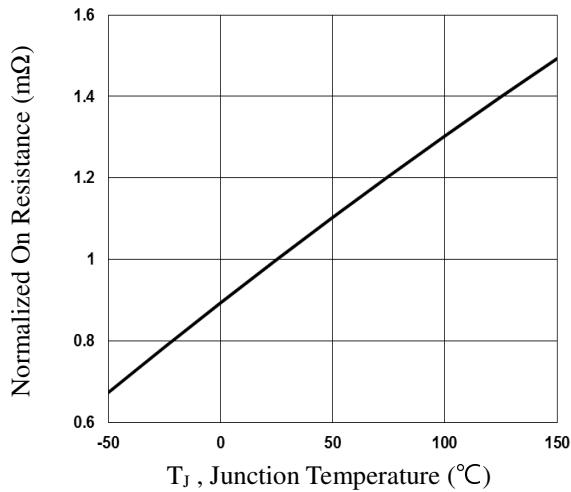
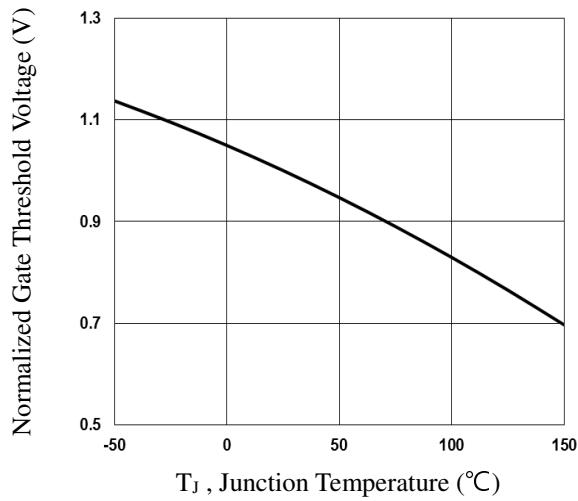
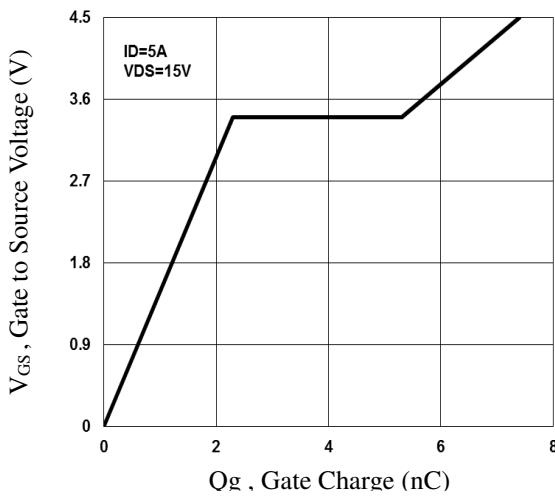
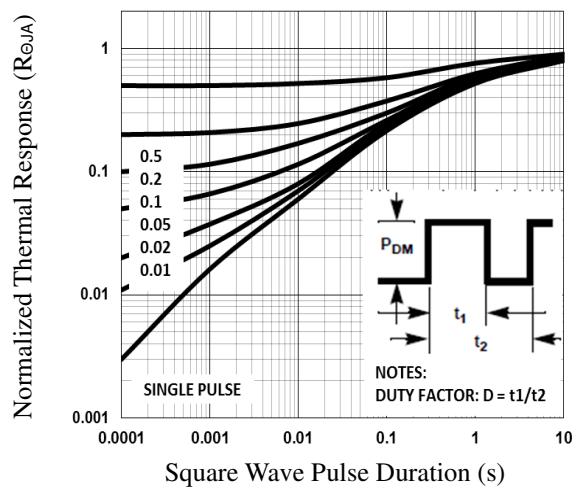
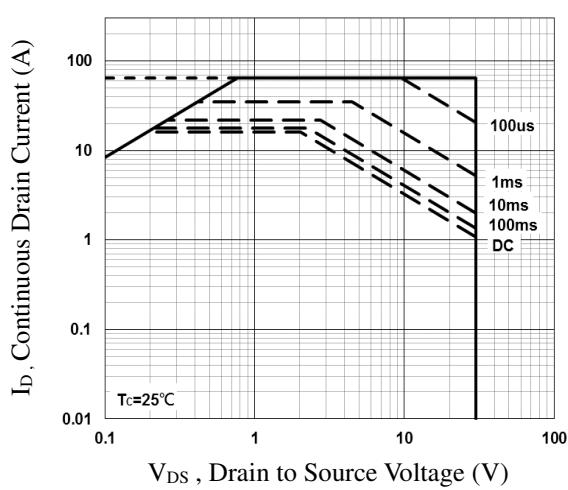
Q_g	Total Gate Charge ^{3, 4}	$V_{\text{DS}}=15\text{V}$, $V_{\text{GS}}=4.5\text{V}$, $I_D=5\text{A}$	---	7.4	12	nC
Q_{gs}	Gate-Source Charge ^{3, 4}		---	2.3	5	
Q_{gd}	Gate-Drain Charge ^{3, 4}		---	3	6	
$\text{T}_{\text{d(on)}}$	Turn-On Delay Time ^{3, 4}	$V_{\text{DD}}=15\text{V}$, $V_{\text{GS}}=10\text{V}$, $R_G=6\Omega$ $I_D=1\text{A}$	---	3.8	7	ns
T_r	Rise Time ^{3, 4}		---	10	19	
$\text{T}_{\text{d(off)}}$	Turn-Off Delay Time ^{3, 4}		---	22	42	
T_f	Fall Time ^{3, 4}		---	6.6	13	
C_{iss}	Input Capacitance	$V_{\text{DS}}=25\text{V}$, $V_{\text{GS}}=0\text{V}$, $F=1\text{MHz}$	---	620	900	pF
C_{oss}	Output Capacitance		---	85	125	
C_{rss}	Reverse Transfer Capacitance		---	60	90	
R_g	Gate resistance	$V_{\text{GS}}=0\text{V}$, $V_{\text{DS}}=0\text{V}$, $f=1\text{MHz}$	---	2.8	5.6	Ω

Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current	$V_G=V_D=0\text{V}$, Force Current	---	---	16	A
I_{SM}	Pulsed Source Current		---	---	32	A
V_{SD}	Diode Forward Voltage	$V_{\text{GS}}=0\text{V}$, $I_s=1\text{A}$, $T_J=25^\circ\text{C}$	---	---	1	V

Note :

- Repetitive Rating : Pulsed width limited by maximum junction temperature.
- The data tested by pulsed , pulse width $\leq 300\text{us}$, duty cycle $\leq 2\%$.
- Essentially independent of operating temperature.


Fig.1 Continuous Drain Current vs. T_c

Fig.2 Normalized R_{DS(on)} vs. T_j

Fig.3 Normalized V_{th} vs. T_j

Fig.4 Gate Charge Waveform

Fig.5 Normalized Transient Response

Fig.6 Maximum Safe Operation Area

P-CH Electrical Characteristics ($T_J=25\text{ }^{\circ}\text{C}$, unless otherwise noted)
Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$, $I_D=-250\mu\text{A}$	-30	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	BV_{DSS} Temperature Coefficient	Reference to $25\text{ }^{\circ}\text{C}$, $I_D=-1\text{mA}$	---	-0.03	---	$\text{V}/\text{ }^{\circ}\text{C}$
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=-30\text{V}$, $V_{GS}=0\text{V}$, $T_J=25\text{ }^{\circ}\text{C}$	---	---	-1	μA
		$V_{DS}=-24\text{V}$, $V_{GS}=0\text{V}$, $T_J=125\text{ }^{\circ}\text{C}$	---	---	-10	μA
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 20\text{V}$, $V_{DS}=0\text{V}$	---	---	± 100	nA

On Characteristics

$R_{DS(\text{ON})}$	Static Drain-Source On-Resistance	$V_{GS}=-10\text{V}$, $I_D=-7\text{A}$	---	24	30	$\text{m}\Omega$
		$V_{GS}=-4.5\text{V}$, $I_D=-4\text{A}$	---	37	46	$\text{m}\Omega$
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D = -250\mu\text{A}$	-1	-1.6	-2.5	V
			---	4	---	$\text{mV}/\text{ }^{\circ}\text{C}$
g_{fs}	Forward Transconductance	$V_{DS}=-10\text{V}$, $I_D=-3\text{A}$	---	9	---	S

Dynamic and switching Characteristics

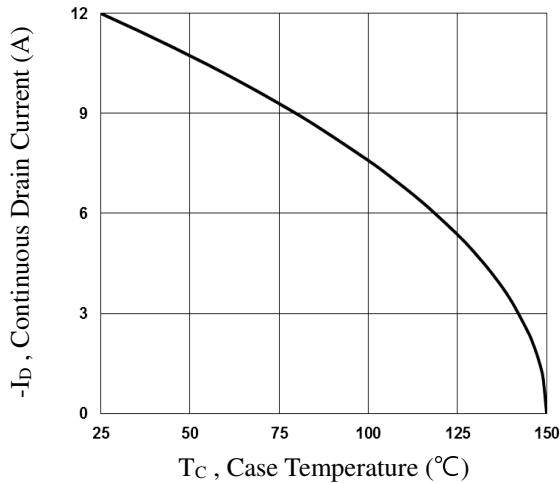
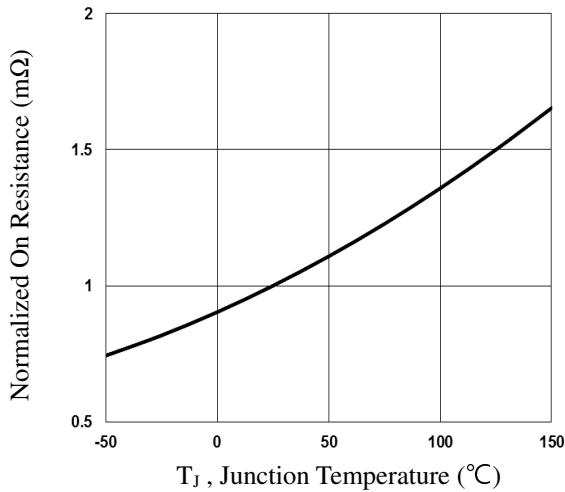
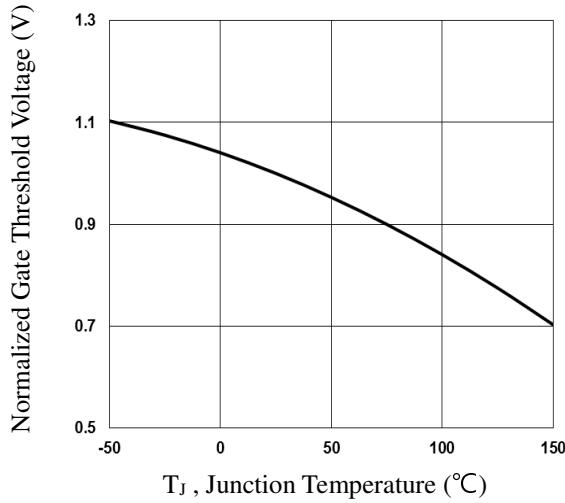
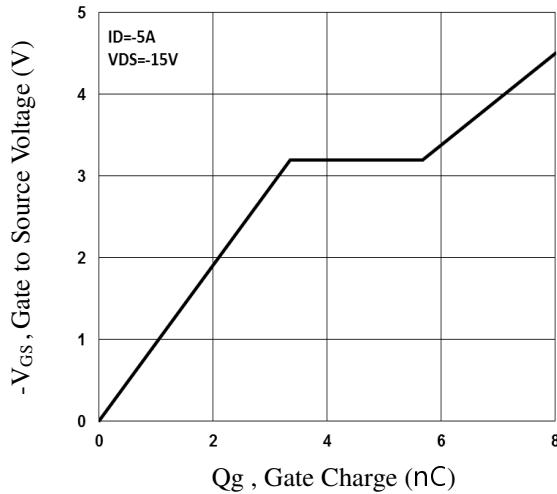
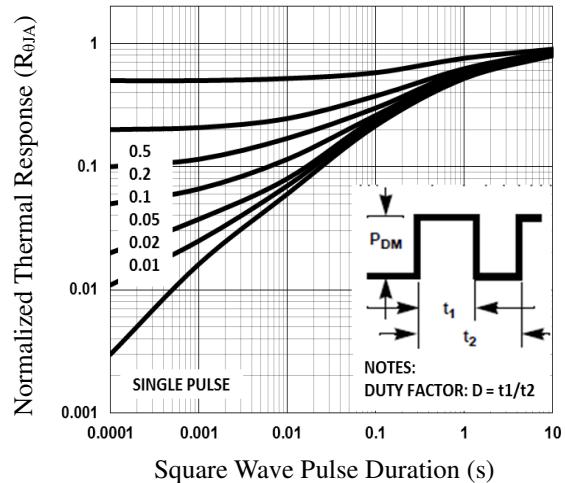
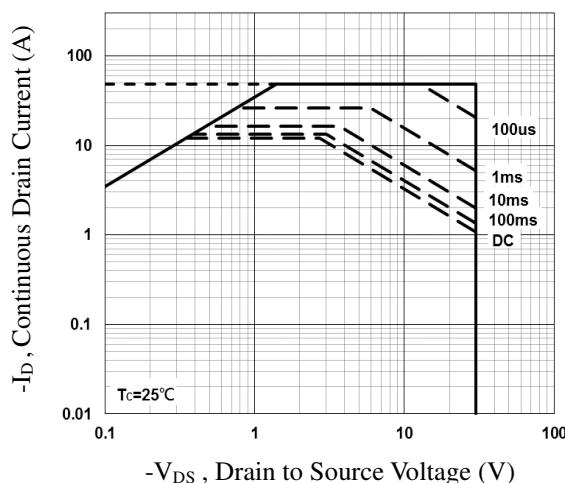
Q_g	Total Gate Charge ^{2, 3}	$V_{DS}=-15\text{V}$, $V_{GS}=-4.5\text{V}$, $I_D=-5\text{A}$	---	8	15	nC
Q_{gs}	Gate-Source Charge ^{2, 3}		---	3.3	6	
Q_{gd}	Gate-Drain Charge ^{2, 3}		---	2.3	5	
$T_{d(on)}$	Turn-On Delay Time ^{2, 3}	$V_{DD}=-15\text{V}$, $V_{GS}=-10\text{V}$, $R_G=6\Omega$ $I_D=-1\text{A}$	---	4.6	9	ns
T_r	Rise Time ^{2, 3}		---	14	26	
$T_{d(off)}$	Turn-Off Delay Time ^{2, 3}		---	34	58	
T_f	Fall Time ^{2, 3}		---	18	35	
C_{iss}	Input Capacitance	$V_{DS}=-15\text{V}$, $V_{GS}=0\text{V}$, $F=1\text{MHz}$	---	757	1280	pF
C_{oss}	Output Capacitance		---	122	210	
C_{rss}	Reverse Transfer Capacitance		---	88	175	

Drain-Source Diode Characteristics and Maximum Ratings

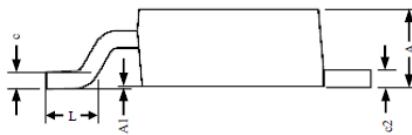
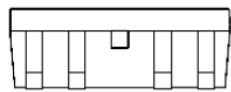
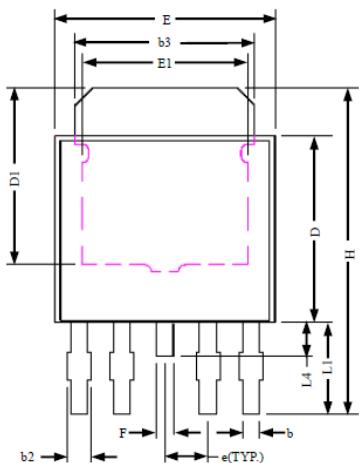
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current	$V_G=V_D=0\text{V}$, Force Current	---	---	-12	A
I_{SM}	Pulsed Source Current		---	---	-24	A
V_{SD}	Diode Forward Voltage	$V_{GS}=0\text{V}$, $I_s=-1\text{A}$, $T_J=25\text{ }^{\circ}\text{C}$	---	---	-1	V

Note :

4. Repetitive Rating : Pulsed width limited by maximum junction temperature.
5. The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
6. Essentially independent of operating temperature.


Fig.1 Continuous Drain Current vs. T_C

Fig.2 Normalized R_{DSON} vs. T_J

Fig.3 Normalized V_{th} vs. T_J

Fig.4 Gate Charge Waveform

Fig.5 Normalized Transient Impedance

Fig.6 Maximum Safe Operation Area

TO252-4L PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	2.400	2.200	0.094	0.087
A1	0.150	0.000	0.006	0.000
B	0.600	0.400	0.024	0.016
b2	0.800	0.500	0.031	0.020
b3	5.500	5.200	0.217	0.205
C	0.508typ.		0.02typ.	
c2	0.550	0.450	0.022	0.018
D	5.800	5.400	0.228	0.213
D1	---	4.570	---	0.180
E	6.800	6.400	0.268	0.252
E1	---	3.810	---	0.150
E	1.27ref.		0.05ref.	
F	0.600	0.400	0.024	0.016
H	10.200	9.400	0.402	0.370
L	1.770	1.400	0.070	0.055
L1	3.000	2.400	0.118	0.094
L4	1.200	0.800	0.047	0.031